

Amendments to the Claims:

This listing of claims will replace the listing of claims, as filed, in the application:

Listing of Claims:

Claim 1.(original): A method of forming a semiconductor device comprising a semiconductor substrate comprising circuitry and terminal means for establishing electrical connection to the circuitry; providing a sheet for forming a further layer of the device, the sheet comprising at least one groove; applying adhesive to at least one of said substrate and said sheet; and aligning said substrate and said sheet in a position such that said at least one groove faces said terminal means and attaching said substrate and said sheet together by means of said adhesive in said position.

Claim 2 (original): A method according to claim 1, wherein the adhesive is applied solely to said sheet.

Claims 3-15 (canceled).

Claim 16 (original): A semiconductor device assembly comprising a semiconductor substrate comprising circuitry and terminal means for establishing electrical connection to the circuitry; and a sheet attached to the substrate by means of adhesive and forming a further layer of the device, the sheet comprising at least one groove facing and aligned with said terminal means.

Claim 17 (original): A semiconductor device assembly according to claim 16,
wherein the terminal means comprise a plurality of bond pads.

Claims 18-32 (canceled).